

RYC2525ZZ-XXXXWN-99 Features:

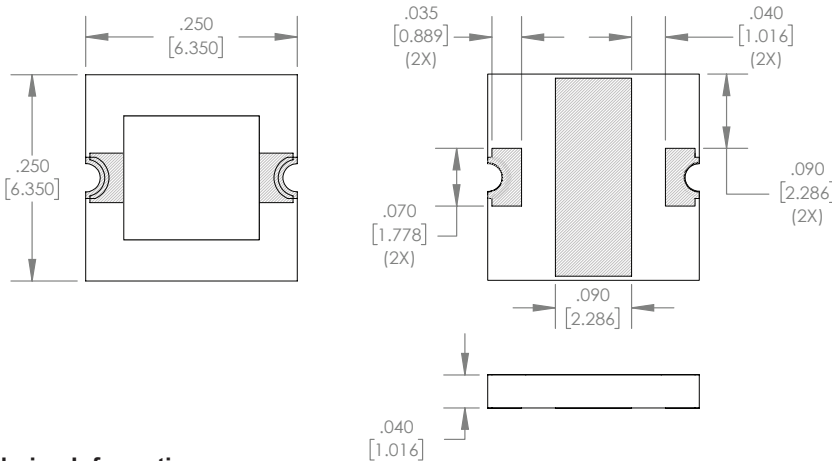
- Wraparound w/ Isolated Center Pad Configuration •
- Solder, Wire-bond, or Epoxy Attachment Available
- Solder or Epoxy Mount Backplane
- Customer Defined Testing Available
- RoHS Compliant Available
- Tape & Reel or Waffle Pack Available (Standard is bulk)
- 1, 2, or 5% Resistor Tolerance Available
- Non-Magnetic Available

RYC2525ZZ-XXXXWN-99 Parameters:

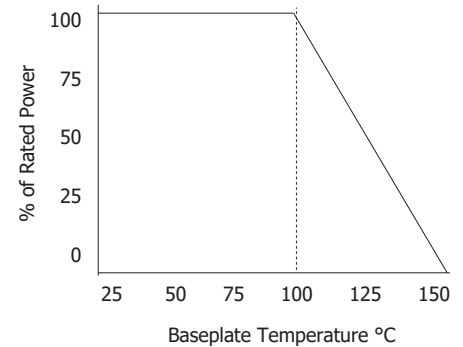
Resistance Range:	0.5Ω - 1MΩ
Rated Power:	100W*
Construction:	Thick Film on BeO
Operating Temperature:	-55 to +150°C

* Rating based on ≤100°C constant baseplate temperature

RYC2525ZZ-XXXXWN-99 Dimensions:



RYC2525ZZ-XXXX □ N-□ □ Power Derating Curve



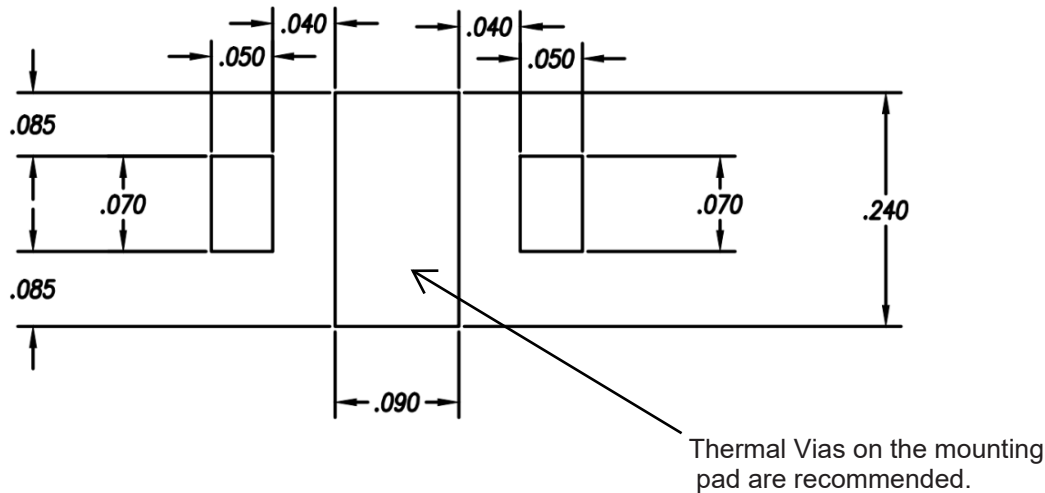
Dimensions in inches [mm]
Tolerance is ± 0.010 [0.254]
unless otherwise stated

Ordering Information:

RYC	2525	ZZ	-	XXXX	W	N	-	99	UU
Prefix for Wraparound Resistor w/ Isolated Backpad									
Size 2525									
		Value Code Examples 10R0 - 10Ω 1000 - 100Ω 1001 - 1KΩ			Tolerance F - 1% G - 2% J - 5%	Normal Inspection Contact factory for additional options		Substrate 99 - 0.040" BeO	Packaging Blank - Bulk TR - Tape and Reel WP - Waffle Pack
Terminal Metallization									
AS -	Tin Lead over Platinum Palladium Gold	RoHS	No	Magnetic	No	Solder	Yes	Epoxy	No
CB -	Tin Lead over Nickel over Silver	No	Yes	Yes	No	Yes	No	No	No
CC -	100% Matte Tin over Copper over Silver	Yes	No	Yes	No	Yes	No	No	No
CT -	100% Matte Tin over Nickel over Silver	Yes	Yes	Yes	No	Yes	No	No	No
HA -	Gold over Platinum Gold I/O Terminals w/ Platinum Palladium Gold Backplane	Yes	No	Yes (Backplane)	Yes	Yes	Yes	Yes (I/O Terminals)	Yes
JA -	Gold over Platinum Palladium Gold	Yes	No	No	No	Yes	Yes	Yes	Yes

Barry Industries reserves the right to change part number and/or process without notification.

RYC2525ZZ-XXXXWN-99 Recommended Footprint:



RYC2525ZZ-XXXX□ N-□ □ Reliability Specifications:

Parameter:	Test Condition:	Results:
Short Time Overload	Apply 1.1x Rated Power for 5 Seconds.	≤ 5.0% Resistance Shift
Rated Load Life	Apply 1/2 Power Under 40°C ±2°C 90 Minutes on/ 30 Minutes off. Repeat for 100 hours	≤ 5.0% Resistance Shift
Moisture Resistance	MIL-PRF-55342 para 4.8.9 95% RH, 25°C - 65°C	≤ 5.0% Resistance Shift
Resistance to Soldering Heat	MIL-STD-202 Method 210 and MIL-PRF-55342 Para 4.8.8.1	≤ 5.0% Resistance Shift
Resistance to Wire-Bonding Exposure	MIL-PRF-55342 Para 4.8.8.2	≤ 5.0% Resistance Shift
Solderability	MIL-PRF-55342 Para 4.8.12	>95% Covered
High Temperature Storage	125°C ±2°C for 500 Hours	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)
Thermal Shock	-65°C to +150°C 30 Minutes Dwell, 5 Cycles	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)

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